

SIZE	QTY	SYM	PLATED	TOL
0.01	226	+	YES	+/-0.003
0.04	1	X	YES	+/-0.003
0.07	2	□	NO	+/-0.003
0.095	7	◇	YES	+/-0.003
0.035	10	⊗	YES	+/-0.003
0.006	8	⊗	YES	+/-0.003
0.008	7	+ ^A	YES	+/-0.003

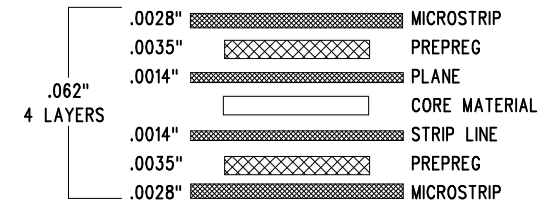
ADDITIONAL REQUIREMENT FOR PROTOTYPE FAB ONLY:

1. OUTGOING INSPECTION REPORT (BASED ON ACTUAL MEASUREMENTS AND CROSS SECTION).

ADDITIONAL REQUIREMENTS FOR PRODUCTION FAB ONLY:

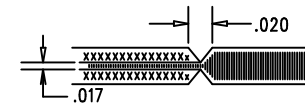
1. PROVIDE COMPLIANCE CERTIFICATES FOR RoHS, REACH AND CONFLICT-FREE MINERALS.
2. SOLDERABILITY BOARD WITH TEST RESULTS.
3. OUTGOING INSPECTION REPORT (BASED ON ACTUAL MEASUREMENTS AND CROSS SECTION).
4. VACUUM PACKED WITH DESICCANT.
5. FULL PANEL WITH NO REJECT

LAYER STRUCTURE



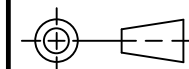
NOTES: UNLESS OTHERWISE SPECIFIED

1. FAB PER IPC-A-600.
2. MATERIAL: -EPOXY FIBERGLASS, NEMA GRADE FR-4
-FINISHED THICKNESS TO BE 0.062" +/- .005"
-TOTAL OF 4 LAYERS WITH 2 OZ. CU ON THE OUTER LAYERS
AND 1 OZ. CU ON THE INNER LAYERS.
-FLAMMABILITY RATING: 94 V-0 MINIMUM.
3. SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN.
0.00" ARE PRIMARY DATUMS.
4. DRILLING: -DRILL HOLES PER SCHEDULE. PLATE THROUGH
HOLES WITH COPPER, 0.001" THICK MIN.
-ALL HOLE SIZES ARE SPECIFIED AFTER PLATING.
-HOLE LOCATION TOLERANCES ARE +/-0.003"
IN RELATION TO CENTER
-FOR VIAS SIZE > 0.01", VIAS HOLES NEED TO BE PLUGGED
AND COVERED WITH SOLDERMASK.
5. FINISH: -SMOBC USING LPI BOTH SIDES, COLOR BLUE.
-GOLD IMMERSION BOTH SIDES.
(LEAD FREE SOLDER CAN BE USED FOR PROTOTYPE)
-FOR SILKSCREEN: BOTH SIDES USE WHITE NON-CONDUCTIVE INK.
6. DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE.
PAD SIZE CAN BE MODIFIED TO MEET END FINISH.
7. PCBs ARE TO BE RoHS COMPLIANT.
8. SCORING FOR PANELIZED PCB:



UNLESS OTHERWISE SPECIFIED

DIMENSIONS ARE IN INCHES
TOLERANCES:
0.XX" = ±0.01"
0.XXX" = ±0.005"
INTERPRET DIM AND TOL
PER ASME Y14.5M-1994
THIRD ANGLE PROJECTION



TITLE: FABRICATION DRAWING
LOW I_Q 40V, 3A
BOOST/SEPIC/INVERTING CONVERTER

SIZE	IC NO.	REV
N/A	LT8333RDD EVAL-LT8333-AZ	2
FILENAME: EVAL-LT8333-AZ-2.PCB		SHT 1 OF 1